IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Lower

CASE: OST-031107

SERIAL NO.: 10/619,933

FILED ON: July 15, 2003

FOR: METHOD FOR MEASURING THE INTENSITY PROFILE OF AN ELECTRON BEAM, IN PARTICLAR A BEAM OF AN ELECTRON-BEAM MACHINING DEVICE, AND/OR FOR MEASURING AN OPTICAL SYSTEM FOR AN ELECTRON BEAM AND/OR FOR ADJUSTING AN OPTICAL SYSTEM FOR AN ELECTRON BEAM, MEASURING STRUCTURE FOR SUCH A METHOD AND ELECTRON-BEAM MACHINING DEVICE

STATEMENT OF BASIS FOR RELEVANCE OF FOREIGN LANGUAGE DOCUMENTS IDENTIFIED IN SUBMITTED SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

ATTENTION OF:

EXAMINER:

Dear Sir:

If any charges or fees must be paid in connection with the following communication, they may be paid out of our Deposit Account No. 50-0545.

Publication Number	Publication Date	Basis for Relevance
DE 37 18 177 A1	December 15, 1988	Device for focusing an electron beam onto a workpiece consists of controlling the focusing current in direct relationship to the voltage measured from the electrons reflected back from the workpiece surface. Enables the burning point of the beam to be exactly focused onto the workpiece surface or to be focused at a constant point below or above the surface irrespective of the unevenness of the surface or of relative movement between beam and surface.

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Jacob D. Koering **51890**

De 101 29 019 A1	January 10, 2002	A metal mark portion made of tungsten has predetermined mark pattern. The metal mark portion is supported by a substrate, and has the line width of about 0.1 mu m or less. For adjusting the focus of electron beam and for measuring the shape of electron beam and for measuring the shape of electron beam in electron beam processing apparatus such as electron microscope, electron beam testing apparatus and electron beam length measurement apparatus. Accurately measures the shape of electron beam as line width is reduced. Reduces focus adjustment time.

Should anything further be required, a telephone call to the undersigned at (312) 226-1818 is respectfully invited.

Respectfully submitted,

Dated: 2-24-04

Jody L. Factor
One of Attorneys for Applicant

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Patent Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on 2-24-04.

Jody L. Factor

Name of Applicant, assignee, applicant's attorney or Registered Representative

Signature

PTO/SB/08A (06-03)
Approved for use through 07/31/2003. OMB 0651-0031
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Substitute for form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 1

Complete if Known	
Application Number	10/619933
Filing Date	7/15/2003
First Named Inventor	Lower
Art Unit	Not yet assigned
Examiner Name	Not yet assigned
Attorney Docket Number	OST-031107

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No.[1]	Document Number Number - Kind Code[2] (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		US-3,752,952	08-14-1973	Ruge et al.	
		US-3,409,799	11-05-1968	Kurzweil et al.	
		US-			
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FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No.[1]	Foreign Patent Document Country Code[3] - Number[4] - Kind Code[5] (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T[6]
		DE 37 18 177 A1	12-15-1988	Schmidt		
		DE 101 29 019 A1	01-10-2002	Takakuwa		
		EP 0 242 993	10-26-1987	The Welding Institute		
		GB 2 132 390 A	07-04-1984	Tokyo Shibaura Denki		

Examiner Signature		Date Considered	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. [1]Applicant's unique citation designation number (optional). [2]See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. [3]Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). [4]For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. [5]Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. [6]Applicant is to place a check mark here if English language Translation is attached.